

| L Number | Hit | Sear h Text | DB | Time stamp |
|-------------|-------|-----------------------------|---|---------------------|
| - | 1006 | 235/494.ccls. | USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 17:55 |
| - | 0 | 235/494.ccls. and chiba.in. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 17:56 |
| - | 0 | jp-223380-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 17:56 |
| - | 9 | "223380" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 17:57 |
| - | 0 | jp-223380-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 17:58 |
| - | 0 | jp-5923512-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 17:58 |
| - | 2 | jp-2000223380-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:00 |
| - | 0 | jp-2175154-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:00 |
| - | 1 | jp-3116919-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:00 |
| - | 15423 | chiba.in. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:02 |

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|---|-------|--|--|-------------------------|
| - | 818 | chiba.in. and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:02 |
| - | 58 | (chiba.in. and semiconductor) and mark | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:05 |
| - | 153 | (chiba.in. and semiconductor) and wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:06 |
| - | 83 | 235/494.ccls. and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:10 |
| - | 8 | (235/494.ccls. and semiconductor) and wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:06 |
| - | 34 | (235/494.ccls. and semiconductor) and mark | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:47 |
| - | 2 | 6305677.pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:16 |
| - | 174 | 269/13.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:18 |
| - | 81423 | semiconductor adj2 wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:19 |
| - | 4744 | (semiconductor adj2 wafer) and mark | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:19 |

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| - | 4500 | ((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:20 |
| - | 61 | ((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:53 |
| - | 22 | semiconductor adj mark | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:52 |
| - | 1602 | 355/53.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:29 |
| - | 1154 | 355/53.ccls. and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:29 |
| - | 1052 | (355/53.ccls. and semiconductor) and wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:29 |
| - | 415 | ((355/53.ccls. and semiconductor) and wafer) and mark | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:30 |
| - | 8 | ((355/53.ccls. and semiconductor) and wafer) and mark) and reproduce | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:32 |
| - | 0 | ((355/53.ccls. and semiconductor) and wafer) and mark) and efface | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:32 |
| - | 5 | ((355/53.ccls. and semiconductor) and wafer) and mark) and erase | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:34 |

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| - | 0 | ((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce adj erased adj marks) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:35 |
| - | 0 | ((355/53. ccls. and semiconductor) and wafer) and mark) and (reproduce erased marks)) and efface | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:35 |
| - | 10 | ((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce erased marks)) and notch | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:35 |
| - | 300 | ((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce erased marks) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:38 |
| - | 0 | ((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce near erased near marks) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:39 |
| - | 0 | ((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce same erased same marks) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:39 |
| - | 121 | ((355/53.ccls. and semiconductor) and wafer) and mark) and identical | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:40 |
| - | 9 | ((355/53.ccls. and semiconductor) and wafer) and mark) and identical) and reproduce\$2 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:44 |
| - | 172 | ((355/53.ccls. and semiconductor) and wafer) and mark) and prevent | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:44 |
| - | 3 | ((355/53.ccls. and semiconductor) and wafer) and mark) and prevent) and erase | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:53 |

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|---|-------|---|---|---------------------|
| - | 354 | 355/43.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:53 |
| - | 84 | 355/43.ccls. and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:53 |
| - | 71 | (355/43.ccls. and semiconductor) and wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:53 |
| - | 1 | ((355/43.ccls. and semiconductor) and wafer) and mark) and erase | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:54 |
| - | 45 | ((355/43.ccls. and semiconductor) and wafer) and mark | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:58 |
| - | 25968 | 355/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:58 |
| - | 2116 | 355/\$.ccls. and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:59 |
| - | 1469 | (355/\$.ccls. and semiconductor) and wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:59 |
| - | 497 | ((355/\$.ccls. and semiconductor) and wafer) and mark | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:59 |
| - | 8 | ((355/\$.ccls. and semiconductor) and wafer) and mark) and erase | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 18:59 |

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| - | 13 | ((355/\$.ccls. and semiconduct r) and wafer) and mark) and r produce | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 19:02 |
| - | 1 | ((((355/\$.ccls. and semiconduct r) and wafer) and mark) and erase) and (((355/\$.ccls. and semiconductor) and wafer) and mark) and reproduce) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/05/30 19:02 |
| - | 6 | (235/494.ccls. and semiconductor) and mark and duplicate | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:51 |
| - | 0 | (235/494.ccls. and semiconductor) and (duplicate adj mark) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:51 |
| - | 3 | (235/494.ccls. and semiconductor) and (duplicate same mark) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:51 |
| - | 0 | (semiconductor adj mark) same duplicate | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:53 |
| - | 0 | ((((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce) and (duplicate same mark) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:53 |
| - | 0 | ((((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce) and (duplicate near mark) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:53 |
| - | 0 | ((((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce) and (duplicate adj mark) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:53 |
| - | 72 | ((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:54 |

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| | 3 | (((semiconductor adj2 waf r) and mark) and (semiconductor adj wafer)) and repr duce) and duplicate | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/09 18:54 |
| | 26645 | 355/\$. ls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/10 12:08 |
| | 102 | 430/13.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/10 12:09 |
| | 435 | 257/620.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/01/10 12:09 |
| | 1104 | 235/494.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 12:08 |
| | 27013 | 355/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 12:08 |
| | 462 | 257/620.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 12:09 |
| | 104 | 430/13.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 12:09 |
| | 1015 | replace same mark | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 12:09 |
| | 99 | (replace same mark) and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 12:12 |

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| - | 3 | ((replace same mark) and semic conductor) and 235/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 12:14 |
| - | 89611 | semiconductor adj wafer | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 12:19 |
| - | 5456 | (semiconductor adj wafer) and mark | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 12:20 |
| - | 2 | ((semiconductor adj wafer) and mark) and (replace near10 mark) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/30 12:20 |